

May 22, 2025

Investor Presentation

Berenberg European Conference
New York



SUSS at a glance



- Hidden champion headquartered in Germany with 75 years track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry, benefiting from structural growth drivers such as Artificial Intelligence
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor IDMs and foundries
- Innovator with relevant network to research institutes and universities

SUSS is part of our digital life!

Milestones in our company's history



1949

Company founded as Karl Süss KG in Munich



1990

Volume production of wafer bonder starts



2000

Coating systems added through acquisition of Fairchild Technologies



2010

Second German site established after acquisition of Hamatech APE



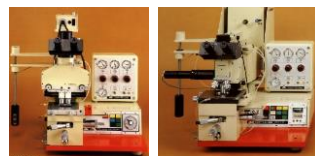
2020

Inkjet printing added to coating expertise through acquisition of PiXDRO



2024

Relaunch of the brand as SUSS



1963

World's first mask aligner SUSS MJB3 developed



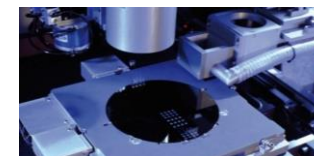
1999

Initial Public Offering at the Frankfurt Stock Exchange completed



2001

Company renamed to SUSS MicroTec



2012

Laser processing technology taken over from newly acquired Tamarack Scientific



2020

Asian production site opened in Hsinchu/Taiwan

Management Board of SUSS MicroTec SE



CFO
Dr. Cornelia Ballwiesser

- Finance & Controlling
- Legal & Compliance
- Risk Management
- Investor Relations
- IT
- ESG



CEO
Burkhardt Frick

- Sales and Service
- Strategy
- HR
- Internal Audit
- Business Units:
Advanced Backend Solutions,
Photomask Solutions



COO
Dr. Thomas Rohe

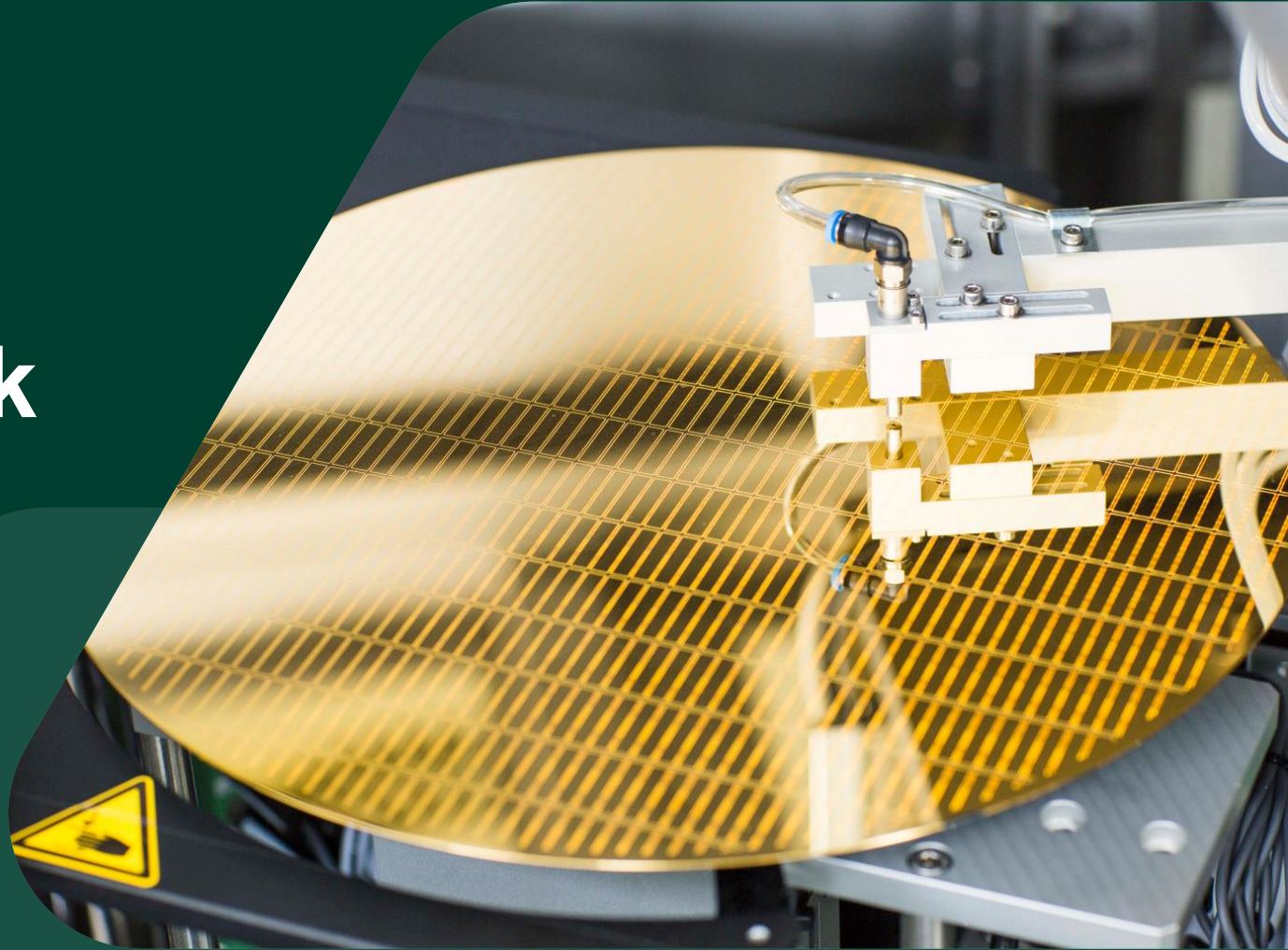
- R&D
- Purchasing
- Production
- Logistics
- Quality Management
- Product Center
- Facility Management

Our corporate vision defines our strategies

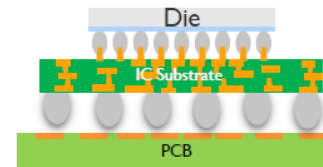
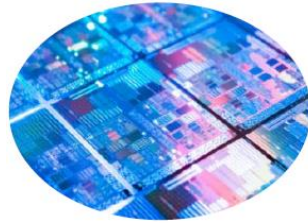


Leader in enabling innovative advanced backend & photomask solutions

Our vision



Our world are the semiconductor frontend and backend process steps



Wafer fabrication

Front-end-of-line Wafer process

- Deposition/coating
- Cleaning
- **Patterning/lithography**¹
- Etching
- Implantation
- Annealing
- **Permanent bonding**
- **Temporary bonding**
- CMP polishing

From middle-of-line to back-end-of-line

Advanced packaging

- Deposition/coating
- Cleaning
- **Patterning/lithography**
- Etching
- Annealing
- CMP polishing
- **Permanent bonding**
- **Temporary bonding**
- **Wafer level packaging**
- Wafer dicing
- Panel-level packaging

Final packaging

- Mounting
- Wire bonding
- Molding encapsulation
- Trim & forming

¹ Only related to Photomask processing

Source: Yole, Lithography and Bonding Equipment for More than Moore 2022

Our two segments, mainly serving the semiconductor industry



Frontend

Advanced Backend

Segments Photomask Solutions

Advanced Backend Solutions



Products

Photomask Equipment



MaskTrack X

Imaging

Mask Aligner
MA200/300



UV Projection
Scanner
DSC300

Coating



ACS300

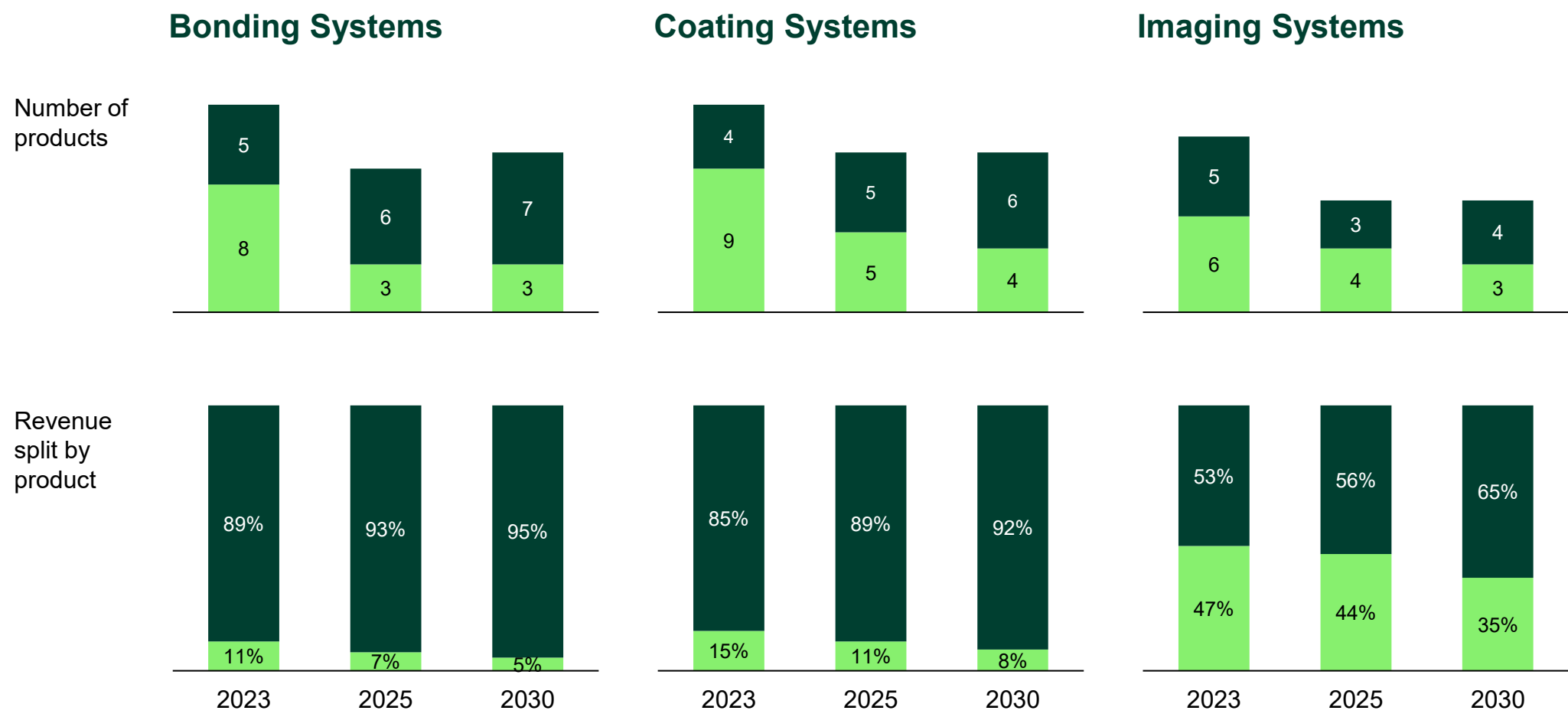
Bonding

XBC300



XB8

Focus on high-volume manufacturing markets while semi-automated tools will be phased-out during next years in Advanced Backend Solutions business unit



 Semi-automated  Automated

Full range of bonding solutions by SUSS



Temporary Bonding

Temporary Bonding
XBS300



Permanent Bonding

Bonding (200 mm)
XBS200



Hybrid Bonding

W2W (up to 200 mm)
XBS200



W2W (up to 300 mm)
XBS300 W2W



De-bonding/Cleaning
XBC300 Gen2



D2W & W2W
XBC300 Gen2 D2W/W2W



D2W
XBC300 Gen2 D2W



Mech. De-bonding
(semi-auto)
DB12T



High-force Bonding (semi-
auto)
SB8 Gen2/XB8



SUSS hybrid bonding solutions – understanding customer's needs



Wafer-to-wafer HB XBS300 W2W

Product launch: 10/2022
Target customers: HVM



Die-to-wafer/wafer-to-wafer HB XBC300 Gen2 D2W/W2W

Product launch: 05/2024
Target customers: Research
institutes, R&D teams of HVM



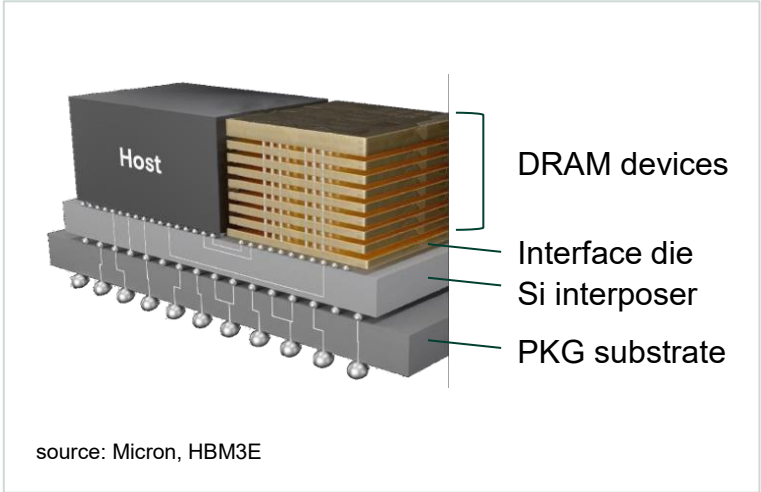
Die-to-wafer HB XBC300 Gen2 D2W

Product launch: H1/2025
Target customers: HVM

We optimize our product solutions to serve our customer's device and manufacturing needs.

HBM roadmap enables SUSS to grow in existing and new markets

in € million	HBM3E	HBM4	HBM4E	HBM5
Expected SOP	2024	2025	2026 or 2027	2027 or 2028
# of DRAM layer acc. to JEDEC	8/12	12	16	16/20
Bonding type in DRAM stack	TCB	TCB	TCB or HB	HB
Thinning of DRAM devices	TBDB	TBDB	TBDB	TBDB



Relevance for SUSS:

1

TBDB remains a crucial process for thinning of DRAM devices used in HBM cube

Growth of existing SUSS TBDB business in line with general HBM market growth

2

Increase of layer number in HBM cube triggers more TBDB capacity for thinning of DRAM devices

Additional growth of SUSS TBDB business in line with higher layer in HBM cube

3

Hybrid bonding will gradually replace Thermal Compression bonding for stacking of DRAM devices

Expansion into this market offers new growth opportunities with SUSS HB solutions

TCB: Thermal compression bonding, HB: hybrid bonding, TBDB: Temporary bonding & de-bonding

We have built up additional temporary bonding capacity in Taiwan

- We added 50+ people in Hsinchu in order increase manufacturing capacity for temporary bonders
- First temporary bonder 'made in Taiwan' has been completed at the beginning of March 2024
- Full capacity available since Q3-2024
- Total manufacturing capacity for temporary bonding equipment (bonder, debonder and cleaner) in Sternenfels and Hsinchu allows us to generate yearly sales of ~ €150 million



New, larger production site in Zhubei (Taiwan) prepares us for further targeted growth

1

Signing

of long-term lease agreement for new production site in Zhubei took place in October 2024.



2

Handover

of the new building to SUSS took place in April 2025.

3

Production start

at the new site is expected in the second half of 2025. The new factory offers the potential to double production capacity under clean room conditions to ~6,300 m².



New production site in Zhubei, Taiwan, was officially handed over to us – we are now equipping it for our use.

Comparison of our production sites in Taiwan



Hsinchu

- In operation since: 2020
- One production site + eight sub locations
- Annual rental expenses: low to mid single-digit million-euro figure
- Annual production capacity: tools worth € 100 to 150 million

Zhubei

- Planned production start: H2 2025
- One big site to consolidate all existing sites and teams
- Annual rental expenses: low to mid single-digit million-euro figure
- Annual production capacity: potential for doubling with corresponding customer demand and depending on the product mix

SUSS reached new highs for sales and profitability in 2024

Financial Results

FY 2024

423.7

in € million

Order intake
FY 2024

+0.8% YoY

446.1

in € million

Sales
FY 2024

+46.6% YoY

40.0

in %

Gross profit margin
FY 2024

+5.9pp YoY

16.8

in %

EBIT margin
FY 2024

+7.7pp YoY

Strong growth and improved profitability made 2024 the most successful year in SUSS' history

in € million	FY 2024	FY 2023	Change
Order intake	423.7	420.5	+ 0.8%
Order book as of December 31	428.4	452.5	- 5.3%
Sales	446.1	304.3	+ 46.6%
Gross profit	178.3	103.9	+ 71.6%
Gross profit margin	40.0%	34.1%	+ 5.9pp
EBIT	75.1	27.8	+ 170.1%
EBIT margin	16.8%	9.1%	+ 7.7pp
Earnings after taxes (continuing operations)	52.1	17.3	+ 201.2%
Net profit ¹	110.3	4.7	n/a
EPS basic (in €, continuing operations)	2.72	0.91	+ 198.9%
EPS basic (in €) ¹	5.77	0.25	n/a
Net cash	122.9	32.8	+ 274.7%
Free cash flow (continuing operations)	25.3	7.9	+ 220.3%
Free cash flow total ¹	96.1	-4.4	n/a
Investments	7.6	4.6	+65.2%
Dividend proposal (in €)	0.30	0.20	+50.0%
Employees as of December 31	1,498	1,207	+ 24.1%

¹ including discontinued operations, i.e. MicroOptics business

- Order intake slightly up year-on-year and managed to offset the decline in demand from China (€ -41.4 million)
- Gross profit margin increased significantly by 5.9pp year-on-year, benefiting from favorable product and customer mix and was volume driven in both segments; EBIT margin also benefited from the under-proportional increase in OPEX (OPEX ratio was 22.8% of sales vs. 25.3% in 2023)
- Net profit of € 110.3 million includes result from discontinued operations (€ 58.3 million), i.e. the sale of our MicroOptics business
- Dividend proposed to increase by 50% to € 0.30 per share, which would correspond to our growth and is approximately 23% of the free cash flow from continuing operations

Segment Overview FY 2024

Advanced Backend Solutions

in € million	FY 2024	FY 2023
Order intake	300.2	294.4
Order book	271.7	286.8
Sales	314.7	214.7
Gross profit	132.8	77.8
Gross profit margin	42.2%	36.2%
EBIT	60.5	20.1
EBIT margin	19.2%	9.4%

- Very high order intake of the previous year once again exceeded by 2%; combined orders in connection with AI applications for temporary bonding solutions and UV projection scanners at around previous year's level; Coating systems order intake improved in H2 2024
- Significant sales growth of € 100.0 million or 46.6% year-on-year, mainly driven by execution of AI-connected bonder orders; bonder sales thus more than tripled year-on-year
- Gross profit margin improved by 6.0pp to 42.2% thanks to high sales volume and favorable product and customer mix

Photomask Solutions

in € million	FY 2024	FY 2023
Order intake	123.5	124.1
Order book	156.7	165.7
Sales	131.4	89.7
Gross profit	47.4	26.5
Gross profit margin	36.1%	29.5%
EBIT	27.2	12.4
EBIT margin	20.7%	13.8%

- Expected normalization of orders from China (- €15.8 million year-on-year) was almost offset by other global markets to reach almost stable order intake
- Strong order book level of ~ € 157 million provides high visibility and capacity utilization in 2025
- Sales growth of 46.5% was realized by increasing the number of slots, additional staff and shortening lead times
- Gross profit margin and EBIT margin benefited from strong product and customer mix as well as from very high business volume

Solid start to the year, particularly in terms of sales growth

Financial Results

Q1 2025

88.1

in € million

Order intake
Q1 2025

-10.4% YoY

123.2

in € million

Sales
Q1 2025

+31.8% YoY

37.9

in %

Gross profit margin
Q1 2025

-1.2pp YoY

16.6

in %

EBIT margin
Q1 2025

+0.7pp YoY

Strong sales growth and improved Free Cash Flow generation

in € million	Q1 2025	Q1 2024	Change
Order intake	88.1	98.3	-10.4%
Order book as of March 31	392.7	456.9	-14.1%
Sales	123.2	93.5	+31.8%
Gross profit	46.7	36.6	+27.6%
Gross profit margin	37.9%	39.1%	-1.2pp
EBIT	20.4	14.9	+36.9%
EBIT margin	16.6%	15.9%	+0.7pp
Earnings after taxes (continuing operations)	15.0	10.4	+44.2%
Net profit ¹	15.0	68.7	-
EPS basic (in €, continuing operations)	0.78	0.54	+44.4%
Net cash	130.0	102.4	+27.0%
Free cash flow (continuing operations)	8.9	-0.4	-
Free cash flow total ¹	8.9	70.1	-
Investments	1.7	1.2	+41.7%
Employees as of March 31	1,509	1,273	+18.5%

- Order intake below previous year, but not a surprise after record in Q4 2024.
- Very positive sales development, driven by both segments (Advanced Backend Solutions: +47.0%; Photomask Solutions: +8.6%).
- Gross profit margin at 37.9% due to change in product/customer mix and preparation for increased UV projection scanner production in Taiwan.
- EBIT margin up by 0.7pp thanks to higher gross profit and disproportionately low OPEX increase.
- Free cash flow from continuing operations improved: slower inventory build-up and change in contract assets were positive drivers.
- Investments still at a moderate level, but will increase significantly in the coming quarters due to the new site in Taiwan

¹ including discontinued operations, i.e. MicroOptics business

Segment Overview Q1 2025

Advanced Backend Solutions

in € million	Q1 2025	Q1 2024
Order intake	54.3	64.6
Order book	242.4	294.8
Sales	82.9	56.4
Gross profit	30.4	25.1
Gross profit margin	36.7%	44.5%
EBIT	9.7	7.2
EBIT margin	11.7%	12.8%

- Order intake below previous year, despite continued strong CoWoS-related demand for our UV projection scanner.
- Sales growth in the first quarter was exceptionally high at +47.0%, mainly driven by execution of AI-related orders for temporary bonding solutions. Imaging and Coating Systems sales were roughly on par with Q1 2024.
- Gross profit margin fell to 36.7% (Q1 2024: 44.5%) mainly due to a change in the product and customer mix, as well as start-up and training costs in Taiwan.

Photomask Solutions

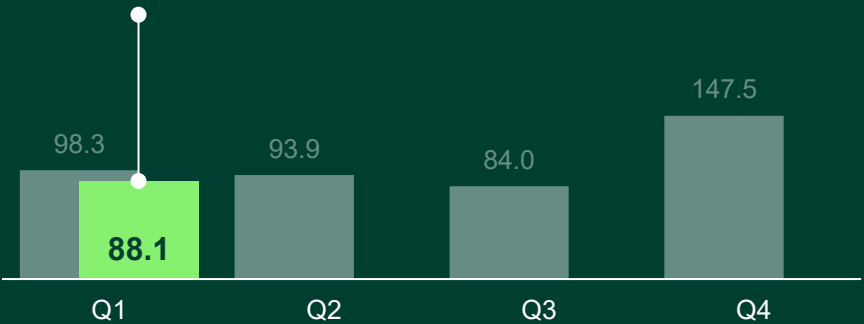
in € million	Q1 2025	Q1 2024
Order intake	33.7	33.7
Order book	150.4	162.1
Sales	40.3	37.1
Gross profit	16.2	12.2
Gross profit margin	40.2%	32.9%
EBIT	13.2	8.2
EBIT margin	32.8%	22.1%

- Order intake was at the same level as in the previous year. The order book of around €150 million continues to offer a high degree of visibility and capacity utilization for FY 2025.
- Sales of € 40.3 million represents growth of 8.6% year-on-year, meaning that we once again worked at full capacity.
- Strong growth in gross profit margin of 40.2 % and EBIT margin of 32.8 % due to favorable customer and product mix and economies of scale from higher business volume.

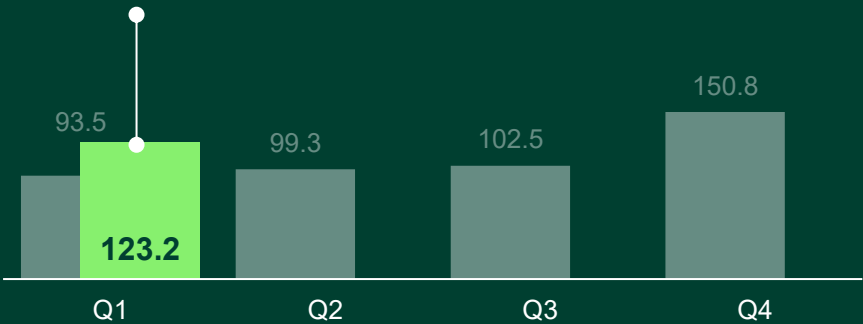
Positive sales trend continued, EBIT margin improved year on year

Excellent sales development and solid order intake after exceptional Q4 2024.

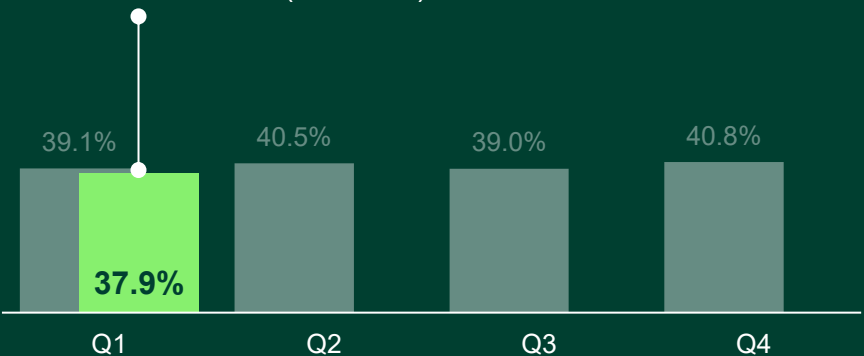
Order intake
€88.1m (Q1 2025)



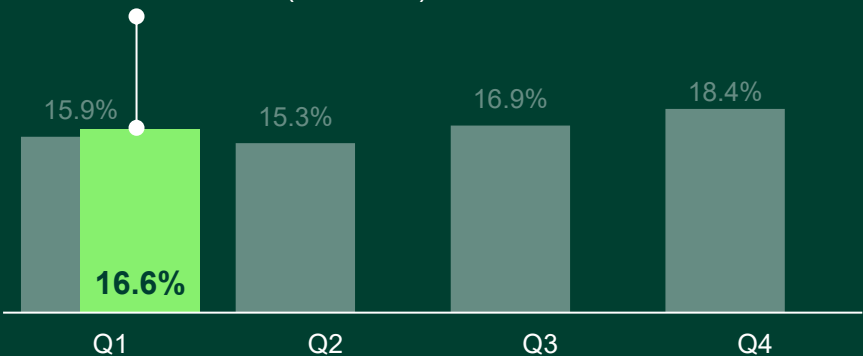
Sales
€123.2m (Q1 2025)



Gross profit margin
37.9% (Q1 2025)



EBIT margin
16.6% (Q1 2025)



■ 2024 ■ 2025

Our two segments with different margin development trends

Order intake
(Q1 2025)

€88.1m

Sales
(Q1 2025)

€123.2m

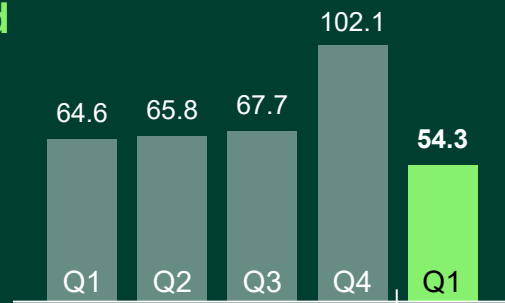
Gross profit margin
(Q1 2025)

37.9%

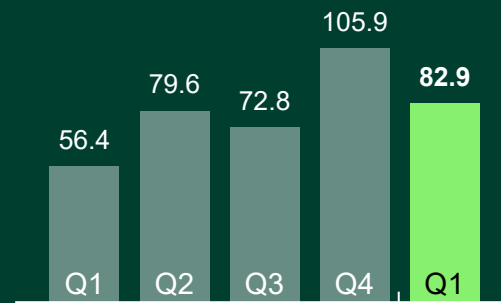
EBIT margin
(Q1 2025)

16.6%

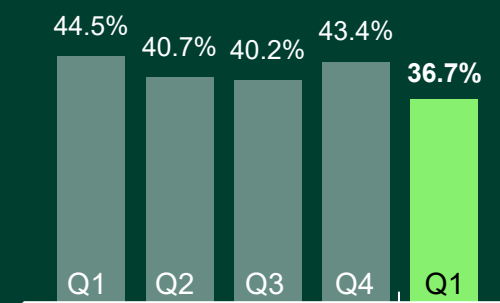
Advanced Backend Solutions (ABS)



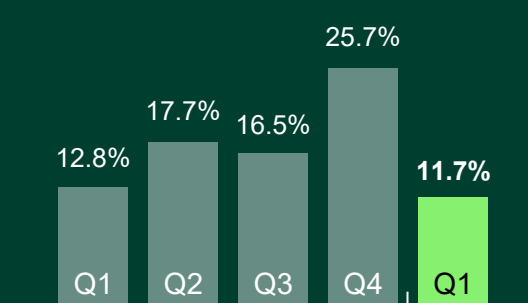
Order intake by quarters



Sales by quarters

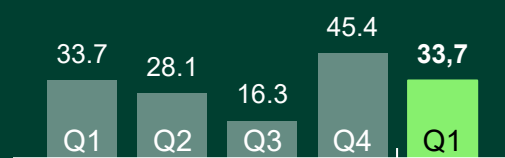


Gross profit margin by quarters

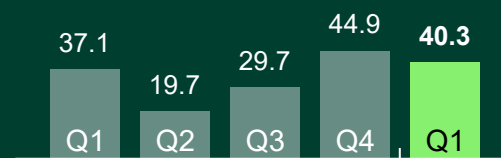


EBIT margin by quarters

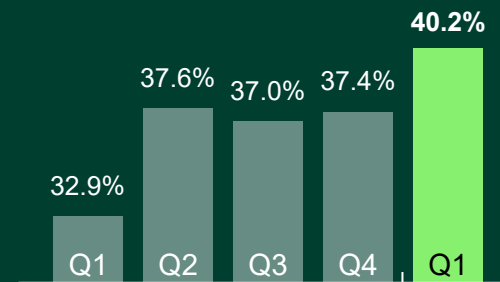
Photomask Solutions (PS)



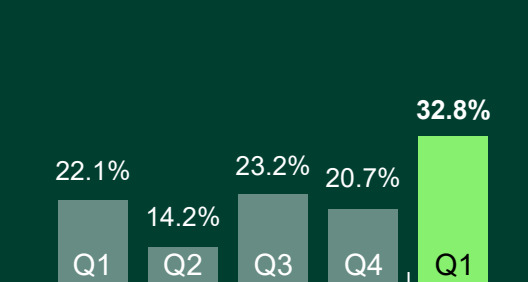
Order intake by quarters



Sales by quarters



Gross profit margin by quarters



EBIT margin by quarters

Q1 sales and current order book provide a solid basis for achieving our sales target for 2025 as a whole

Sales achieved in the first quarter of 2025

€ 123.2 million

Order book as of March 31, 2025,
of which the **majority** is expected to be executed
in 2025

€ 392.7 million

We confirm our forecast for the full year 2025, but the risk situation has deteriorated due to the current tariff and trade dispute.

Guidance 2025

(as of March 27, 2025)



Macroeconomic risks have increased: The full rollout or even further tightening of the initially announced US tariffs, further significant changes in exchange rates and substantial customer project postponements or order cancellations are not factored in.

Expected development in our segments in 2025

Advanced Backend Solutions



Sales expectation

Growth in the mid single-digit percentage range



Profitability expectation

Slight decline in gross profit margin and EBIT margin due to minor change in product/customer mix and higher R&D expenses

Photomask Solutions



Sales expectation

Growth of 10 to 20 % year-on-year



Profitability expectation

Higher sales volume and better product and customer mix is expected to positively impact gross profit margin and EBIT margin

Market Demand Outlook



Imaging Systems: Higher demand compared to 2024 expected, especially for our UV projection scanner (linked to CoWoS)



Coating Systems: Improved order situation in the second half of 2024 is expected to continue in 2025, e.g., due to foundry and OSAT customers

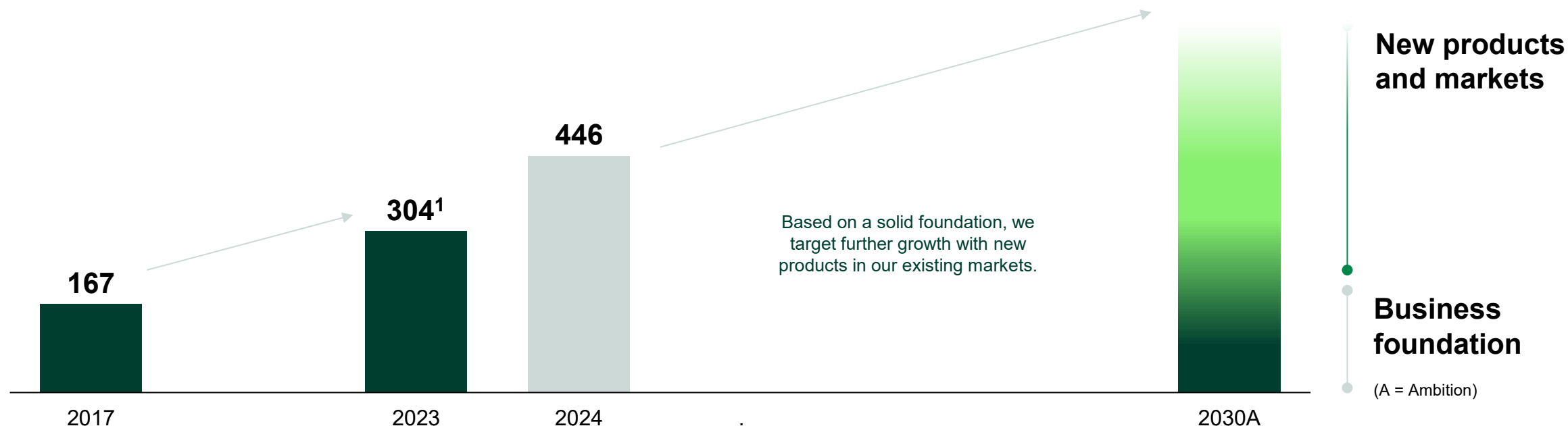


Bonding Systems: Slight decline in order intake expected as follow-up orders cannot keep pace with the initial capacity build-up of the last two years



- New business expected slightly below 2024 level due to normalized demand from China
- Additional momentum from the launch of our new high-end cleaner and a new mid-end cleaner, both planned for 2026, is anticipated towards the end of 2025 at the earliest

Based on our business foundation we see further potential beyond



1

Major growth drivers 2023

Converting high order backlog in Photomask Solutions and Bonder business into sales growth

2

Major growth drivers 2024

- Bonding (especially with regard to AI-driven demand for temporary bonders)
- Photomask Solutions

3

Major growth drivers 2030

- General expected market growth in our core businesses (lithography, bonding, photomask)
- Hybrid Bonding
- Wafer Cleaning

¹ Excluding MicroOptics

Investor Relations information

Conference and Roadshow Calendar

- **May 21, 2025**
Chicago Roadshow, hosted by Jefferies
- **May 22, 2025**
Berenberg European Conference, New York City
- **May 27, 2025**
db European Champions Conference, Frankfurt
- **June 12, 2025**
Warburg Highlights Conference, Hamburg
- **November 17, 2025**
SUSS Capital Markets Day, Garching/Munich

There may be changes to the SUSS conference and roadshow schedule.

Financial Calendar

- **May 8, 2025**
Q1 Report 2025
- **June 3, 2025**
Annual General Meeting
- **August 7, 2025**
Half Year Report 2025
- **November 6, 2025**
Q3 Report 2025

Disclaimer

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SUSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.

Thank you

Growing Innovation



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